

Title (en)

A method for providing a polyolefin resin substrate with an adhesive layer.

Title (de)

Verfahren zur Ausrüstung eines Polyolefinharz-Substrats mit einer Klebeschicht.

Title (fr)

Procédé pour munir un substrat de résine polyoléfinique d'une couche adhésive.

Publication

**EP 0356886 A2 19900307 (EN)**

Application

**EP 89115482 A 19890822**

Priority

JP 21926588 A 19880901

Abstract (en)

A method for providing a polyolefin resin substrate with an adhesive coating having high adhesiveness and thermal resistance comprising the following steps: 1. coating the surface of said polyolefin substrate with a primer film having at least 2 hydroxy groups, and 2. coating said primer film with a molten layer of moisture setting hot melt urethane adhesive composition comprising a urethane prepolymer containing at least 2 NCO radicals. s

IPC 1-7

**C08G 18/62**; **C09J 7/02**; **C09J 175/04**

IPC 8 full level

**B29C 65/40** (2006.01); **C08G 18/08** (2006.01); **C08G 18/62** (2006.01); **C08J 5/12** (2006.01); **C09J 5/02** (2006.01); **C09J 5/06** (2006.01); **C09J 7/22** (2018.01); **C09J 7/35** (2018.01); **C09J 175/04** (2006.01); **B29K 23/00** (2006.01)

CPC (source: EP US)

**C08G 18/08** (2013.01 - EP US); **C08G 18/6208** (2013.01 - EP US); **C09J 7/22** (2017.12 - EP US); **C09J 7/35** (2017.12 - EP US); **C09J 175/04** (2013.01 - EP US); **C08G 2170/20** (2013.01 - EP US); **Y10T 428/2843** (2015.01 - EP US); **Y10T 428/2848** (2015.01 - EP US); **Y10T 428/31587** (2015.04 - EP US)

Cited by

US6673193B1; EP2031001A1; KR20110059876A; CN103254866A; WO0036038A1; WO2009027508A1; WO2010030519A1

Designated contracting state (EPC)

AT BE CH DE ES FR GB GR IT LI LU NL SE

DOCDB simple family (publication)

**EP 0356886 A2 19900307**; **EP 0356886 A3 19910130**; **EP 0356886 B1 19940629**; AT E107951 T1 19940715; CA 1326978 C 19940215; DE 68916493 D1 19940804; DE 68916493 T2 19941013; ES 2056165 T3 19941001; JP H0267121 A 19900307; JP H0757812 B2 19950621; US 5045393 A 19910903

DOCDB simple family (application)

**EP 89115482 A 19890822**; AT 89115482 T 19890822; CA 610148 A 19890901; DE 68916493 T 19890822; ES 89115482 T 19890822; JP 21926588 A 19880901; US 39470089 A 19890816